

# Product Change Notification - KSRA-27FAPU261

### Date:

#### 15 Aug 2019

### Product Category:

8-bit Microcontrollers; Touch Controllers; Capacitive Touch Sensors

Affected CPNs:

### 7

### Notification subject:

CCB 3042 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (3x3x0.9mm) package at NSEB assembly site

#### Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

### **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (3x3x0.9mm) package at NSEB assembly site

#### **Pre Change:**

Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and EFTEC-64T lead frame material

### **Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, G700LTD molding compound material and C194 lead frame material

### Pre and Post Change Summary:

	Pre C	hange	Post Change				
Accomply Site	UTAC Thai I	_imited LTD.	UTAC Thai Limited LTD.				
Assembly Site	(NS	EB)	(NSEB)				
Wire material	Au \	Nire	CuPdAu Wire				
Die attach material	8200T	8600	8600				
Molding compound	G770HCD	G700LTD	G700LTD				
material							
Lead frame material	EFTE	C-64T	C194				

#### Impacts to Data Sheet:

None

Change Impact:

### None

### **Reason for Change:**

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

### Change Implementation Status:

In Progress

### **Estimated First Ship Date:**

March 19, 2018 (date code: 1812)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts



#### Time Table Summary:

	August 2017				>	February 2018			March 2018						
Workweek	31	32	33	34	35	/	05	06	07	08	09	10	11	12	13
Initial PCN Issue	Х														
Date	^														
Qual Report										Х					
Availability										^					
Final PCN Issue										Х					
Date										^					
Estimated														Х	
Implementation Date														^	

### Method to Identify Change:

Traceability code

# **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report **Revision History:** 

August 02, 2017: Issued initial notification.

August 31, 2017: Re-issued initial notification to include CCB 3074.

**February 19, 2018:** Issued final notification. Attached the Qualification Report. Update subject to remove CCB 3074. Revised the affected parts list. Provided estimated first ship date on March 19, 2018.

**August 15, 2019:** Re-issued final notification to specify the package size (3x3x0.9mm) in the subject and description of change and update the affected CPN list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### Attachment(s):

PCN\_KSRA-27FAPU261\_Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

# **Terms and Conditions:**

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Affected Catalog Part Numbers (CPN)

MTCH112-I/MF MTCH112T-I/MF MTCH810-I/MF MTCH810T-I/MF PIC12F1501-E/MF PIC12F1501-I/MF PIC12F1501T-E/MF PIC12F1501T-I/MF PIC12F1571-E/MF PIC12F1571-I/MF PIC12F1571T-I/MF PIC12F1572-E/MF PIC12F1572-E/MFC02 PIC12F1572-I/MF PIC12F1572T-E/MFC02 PIC12F1572T-I/MF PIC12F1612-E/MF PIC12F1612-I/MF PIC12F1822-E/MF PIC12F1822-I/MF PIC12F1822-I/MF043 PIC12F1822T-E/MF PIC12F1822T-I/MF PIC12F1840-E/MF PIC12F1840-H/MF PIC12F1840-I/MF PIC12F1840T-E/MF PIC12F1840T-I/MF PIC12LF1501-E/MF PIC12LF1501-I/MF PIC12LF1571-E/MF PIC12LF1571-I/MF PIC12LF1572-E/MF PIC12LF1572-I/MF PIC12LF1572T-I/MF PIC12LF1612-E/MF PIC12LF1612-I/MF PIC12LF1822-E/MF PIC12LF1822-I/MF PIC12LF1822-I/MF023 PIC12LF1822-I/MFC02 PIC12LF1822T-I/MF PIC12LF1840-E/MF PIC12LF1840-I/MF PIC12LF1840T-I/MF